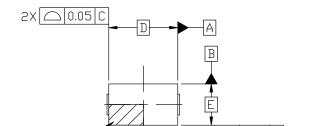


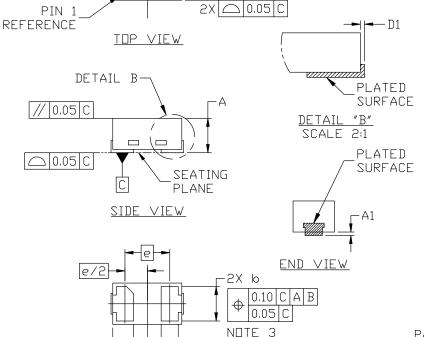
XDFNW2 1.00x0.60x0.50, 0.65P CASE 521AE ISSUE B

DATE 17 JAN 2024

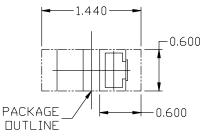


NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- 2. ALL DIMENSION ARE IN MILLIMETERS.
- 3. DIMENSION & APPLIES TO THE PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 FROM THE TERMINAL TIP.



DIM	MILLIMETERS			
	MIN.	N□M.	MAX.	
Α	0.450	0.500	0.550	
A1			0.050	
b	0.450	0.500	0.550	
D	1.000 BSC			
D1			0.050	
E	0,600 BSC			
е	0.650 BSC			
L	0,220 REF			
L1	0,240	0.285	0.340	



RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR
Pb-FREE STRATEGY AND SOLDERING DETAILS,
PLEASE DOWNLOAD THE ON SEMICONDUCTOR
SOLDERING AND MOUNTING TECHNIQUES
REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

BOTTOM VIEW



XX = Specific Device Code

M = Date Code

2X L1

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	XDFNW2 1.00x0.60x0.50, 0.65P		PAGE 1 OF 1	

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